

HVC131

Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0420-0300

(Previous: ADE-208-422B)

Rev.3.00 Oct 29, 2004

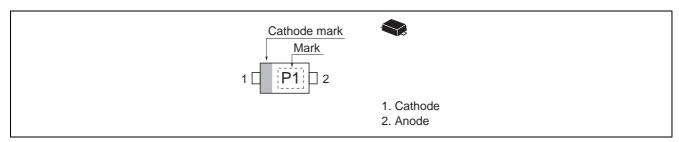
Features

- Low capacitance. (C = 0.8 pF max)
- Low forward resistance. (rf = $1.0 \Omega \text{ max}$)
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC131	P1	UFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

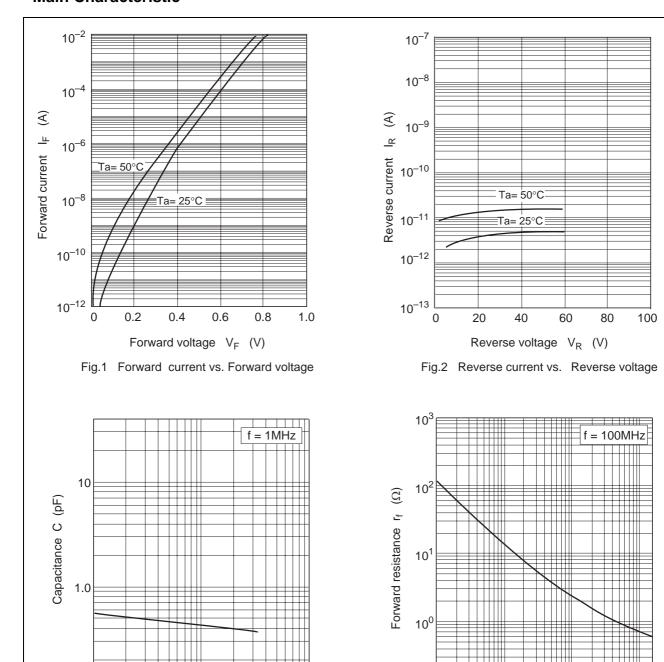
Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM}	65	V
Reverse voltage	V _R	60	V
Forward current	I _F	100	mA
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R			0.1	μΑ	V _R = 60 V
Forward voltage	V _F	_	_	1.0	V	I _F = 10 mA
Capacitance	С	_	_	0.8	pF	V _R = 1 V, f = 1 MHz
Forward resistance	r _f	_	_	1.0	Ω	I _F = 10 mA, f = 100 MHz

Main Characteristic



100

0.1

1.0

10

Reverse voltage V_R (V)

Fig.3 Capacitance vs. Reverse voltage

10⁻¹

 10^{-3}

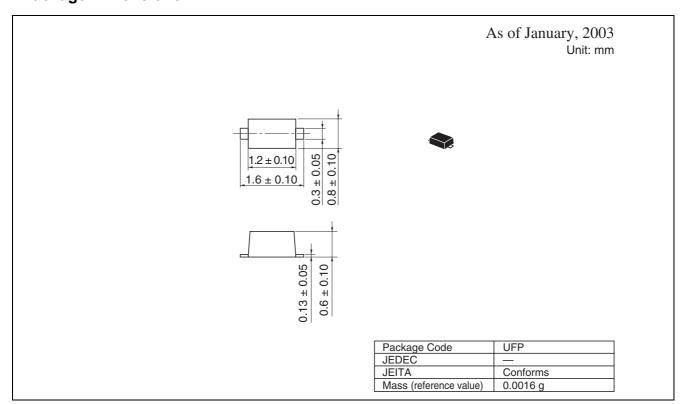
Forward current I_F (A)

Fig.4 Forward resistance vs. Forward current

 10^{-4}

 10^{-2}

Package Dimensions



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